ON Semiconductor®



General Announcement

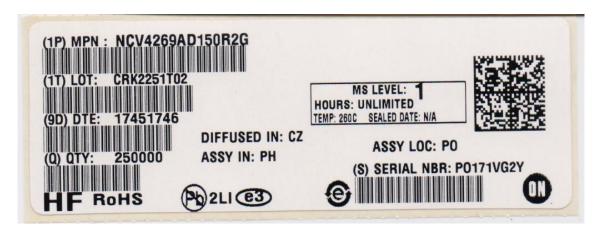
Document # :GA22403X Issue Date: 26 October 2018

Title of Change:	ON Semiconductor MPN Label with 2D Barcode
Effective date:	26 October 2018
Contact information:	Contact your local ON Semiconductor Sales Office or < Dusan. Zelenay@onsemi.com>
Type of notification:	ON Semiconductor considers this change approved.
Change category:	☐ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other MPN LABEL
Change Sub-Category(s): Manufacturing Site Change/Ac Manufacturing Process Change	
Sites Affected:	ON Semiconductor Sites: None External Foundry/Subcon Sites: None

Description and Purpose:

The Electronic Components Industry Association (ECIA) is a global association of electronic manufacturers and approved distributors. ECIA is now providing directive to use the 2D barcode on primary packaging labels. The 2D barcode will contain all the information in the ON Semiconductor MPN (Manufacturer's Part Number) label today.

- The allowed 2D barcode types that can be used are Data Matrix and PDF-417. ON will be using **Data Matrix** with Symbol Type of **ECC 200**. Data inside the barcode should have field identifiers following the industry standards.
- The following fields are mandatory in the 2D Barcode:
 - Part Number (1P)
 - Lot Number (1T)
 - Date Code (9D)
 - Quantity (Q)
 - Country of Manufacture (4L)
 - Serial Number (S)
- · The data should be properly separated with the correct symbols for 2D barcode type (EOT, RS, GS)
- There are no changes to the data barcoded in 3 of 9 technology. All fields are same and in same position on the label.
- This will be a phased implementation of the 2D labels by manufacturing site. We expect to complete this rollout late 2018 to early 2019.



Example Label Only

List of Affected Standard Parts:

This is a General Announcement. General Announcements do not contain a specific list of affected devices. ON Semiconductor uses these announcements when all or no devices are affected.

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